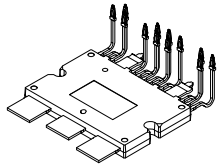


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

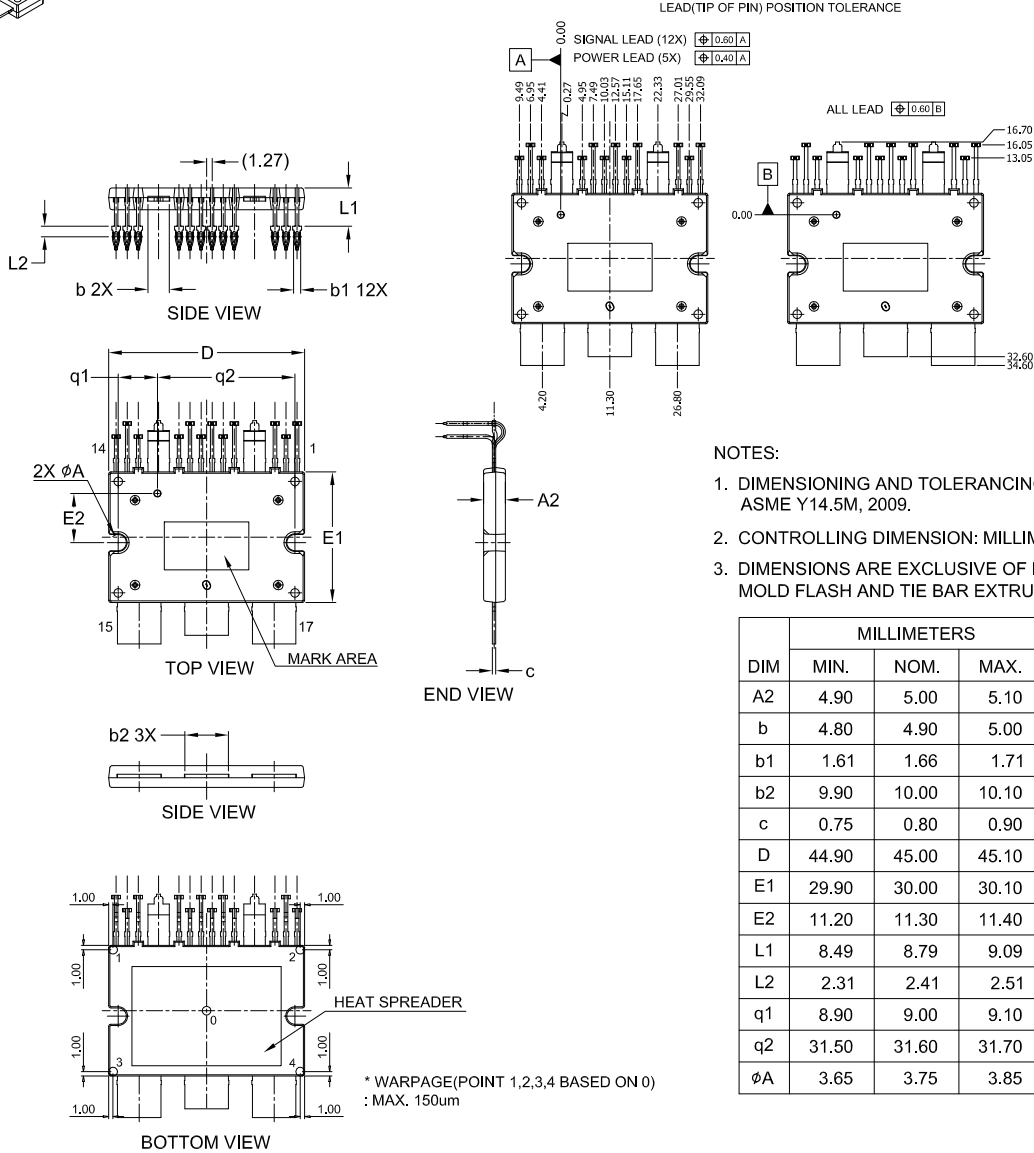


APM17-MFA, AUTOMOTIVE MODULE

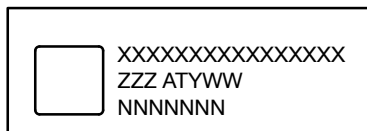
CASE MODBM

ISSUE A

DATE 12 OCT 2022



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
 ZZZ = Assembly Lot Code
 A = Assembly Site
 T = Test Site
 Y = Year
 WW = Work Week
 NN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "u", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	APM17-MFA, AUTOMOTIVE MODULE	PAGE 1 OF 1

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